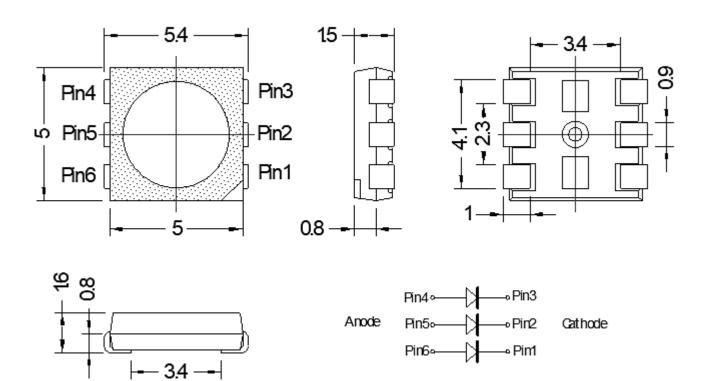


5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

# **PACKAGE OUTLINES**



Items	Materials
Encapsulating Resin	Silicone
Package	Heat-Resistant Polymer
Dice	InGaN
Electrodes	Ag Plating Copper Alloy
Emitted Color	Blue
Viewing Angle	120 Deg

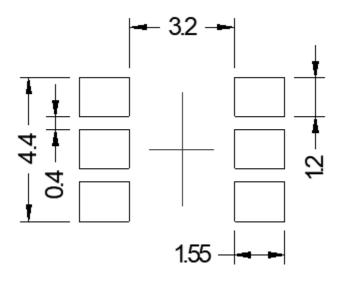
# Notes:

- 1. All dimensions are in millimeters, tolerance is 0.2mm.
- 2. Electrical Connection between all cathodes is recommended.



 $5.4 \times 5.0 \times 1.5$ mm Blue Tri-Chip SMD LED

# RECOMMENDED SOLDERING PAD PATTERN



Unit=mm.



 $5.4 \times 5.0 \times 1.5$ mm Blue Tri-Chip SMD LED

# **ABSOLUTE MAXIMUM RATINGS**

(Ta=25°C)

Parameter	Symbol	Value	Unit
DC Forward Current	I <sub>F</sub>	225	mA
Peak Pulsed Forward Current	I <sub>FP</sub>	300	mA
Power Dissipation	P <sub>d</sub>	714	Mw
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>OPR</sub>	-30 ~ +85	°C
Storage Temperature	T <sub>STG</sub>	-40 ~ +100	°C
Solder Temperature	T <sub>SOL</sub>	260°C for 5 sec	

Note: Ifp= Pulse Width≤10ms, Duty Ratio≤1/10.

# **OPTICAL-ELECTRICAL CHARACTERISTICS**

(Ta=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Forward Voltage	V <sub>F</sub>			3.1	3.4	V
Luminous Intensity	I <sub>V</sub>		1500	2400	3200	mcd
Luminous Flux	ØV	1 450m A	5.0	7.0	8.8	mlm
Dominant Wavelength	$\lambda_{D}$	I <sub>F</sub> =150mA	455	460	465	nm
Peak Wavelength	$\lambda_{P}$			465		nm
Spectral Half Width	Δλ1/2			20		nm
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V		-	50	μΑ

Note: Measurement uncertainty of luminous intensity ±10%



5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

## **LUMINOUS INTENSITY BIN TABLE**

(IF=150mA)

Rank name	Min	Max	Unit
R	1500	1900	
S	1900	2500	mcd
Т	2500	3200	

Note: Tolerance for each bin limit is ±15%.

#### **COLOR BIN TABLE**

(IF=150mA)

Rank name	Min	Max	Unit
1	455	460	
2	460	465	nm

Note: Tolerance for each bin limit is ± 1nm.

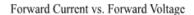
#### Notes:

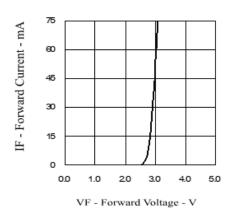
- 1. One delivery will include several color ranks and  $I_{V}$  ranks of products. The quantity ration of different ranks is decided by AOP.
- 2. Bin name typed on the Label: IV rank + Color Rank. For example: BIN R2 Means IV: 1500-1900mcd and Color: 460nm ~ 465nm.
- 3. Static Electricity or surge voltage will damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- 4. AOP has the right to update the information without notice. Please double confirm the spec details before placing an order.



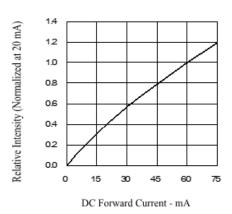
5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

# **ELECTRICAL-OPTICAL CHARACTERISTICS**

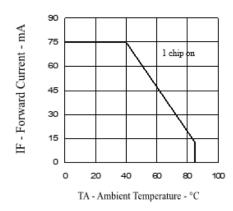




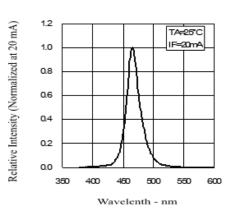
# Relative Intensity vs. Forward Current



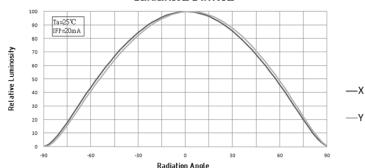
# Forward Current vs. Ambient Temperature



# Relative Intensity vs. Wavelength



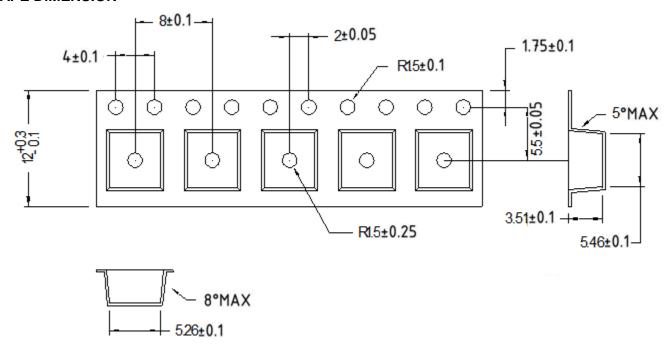
## **Radiation Pattern**



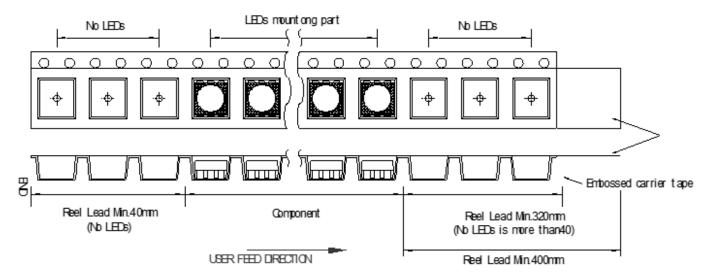


5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

## TAPE DIMENSION



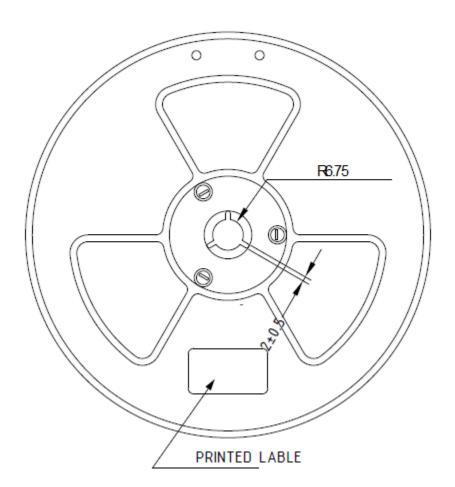
# Tape leader and trailer dimension

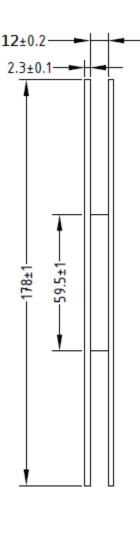




5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

# **REEL DIMENSION**





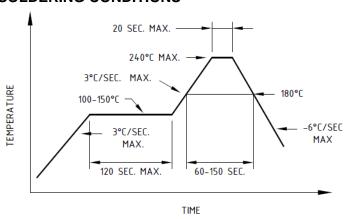
# Notes:

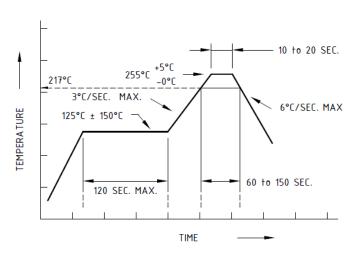
- 1. Empty component pockets sealed with top cover tape.
- 2. 12mm tape, 7 inch reel-1000 pieces per reel.
- 3. All dimension are in millimeters.
- 4. If the package is opened for more than 48 hours, baking is required.
- 5. Baking recommended conditions  $60 \pm 5$  °C for 20 hours.



5.4 x 5.0 x 1.5mm Blue Tri-Chip SMD LED

## **SOLDERING CONDITIONS**





Recommended reflow soldering profile

Recommended Pb-free reflow soldering profile

## Notes:

- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a
  double head soldering iron should be used. It should be confirmed beforehand whether the
  characteristic of the LEDs will or will not be damaged by repairing.
- 2. Reflow soldering should not be done more than two times.
- 3. When soldering, do not put stress on the LEDs during heating.
- 4. After soldering, do not warp the circuit board.

## MOISTURE SENSITIVITY

AOP's SMD LED are shipped in sealed, moisture-barrier bags (MBB), designed for long shelf life. If SMD LED is exposed with moist environments before soldering, this may cause damage to SMD LED during soldering (reflow operation).

Storage/Floor time

Condition	Temperature(C)	Humidity(RH)	Period of Time
Before Open	30	60	6 month from shipping date
After Open	30	60	Within 48 hours

- 1. MSL of this product are MSL4, please see IPC/JEDEC STD020D for more detail.
- 2. LEDs reach floor time may be damaged while soldering/reflow processing, please discard the LED.
- 3. If RH indicator show 60% RH when package is unsealed, please bake/discard the LED.

#### **RESEAL**

- 1. AOP's aluminum MBB may reuse as to reseal the unused LED if MBB has not damaged or has any holes in it.
- 2. Moisture absorbent material (Silica gel) may reuse if it does not become pink.
- 3. Proper resealed LED's floor time will NOT RESET, only stop counting until open
- 4. If RH indicator card show 60% RH when open the package, please bake/discard the package.